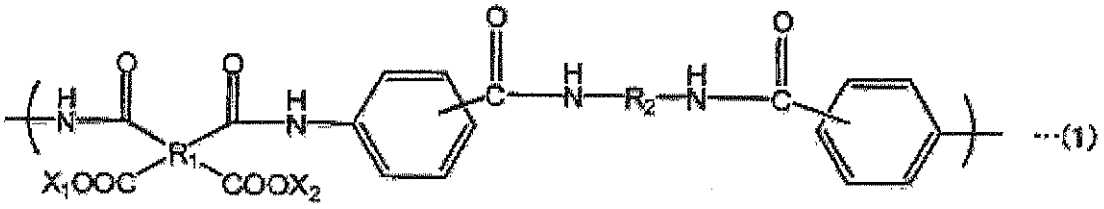
ABSTRACT

A polyamic acid resin composition, a polyimide resin composition, and a polyimide-oxazole resin composition, of which heat-treated films have excellent heat resistance, light transmittance and low birefringence, and a flexible substrate containing the same are provided. The polyamic acid resin composition includes: (a) a polyamic acid including as a main component a structural unit represented by the general formula (1); and (b) a solvent,



wherein in the general formula (1), X_1 and X_2 each independently represent a hydrogen atom or a monovalent organic group having 1 to 10 carbon atoms; R_1 represents a tetravalent organic group having 4 to 40 carbon atoms with a monocyclic or condensed polycyclic alicyclic structure, or a tetravalent organic group having 4 to 40 carbon atoms with organic groups each having a monocyclic alicyclic structure wherein the organic groups are linked to each other directly or via a cross-linked structure; and R_2 represents a divalent organic group having 2 to 40 carbon atoms with at least two hydroxyl groups.